

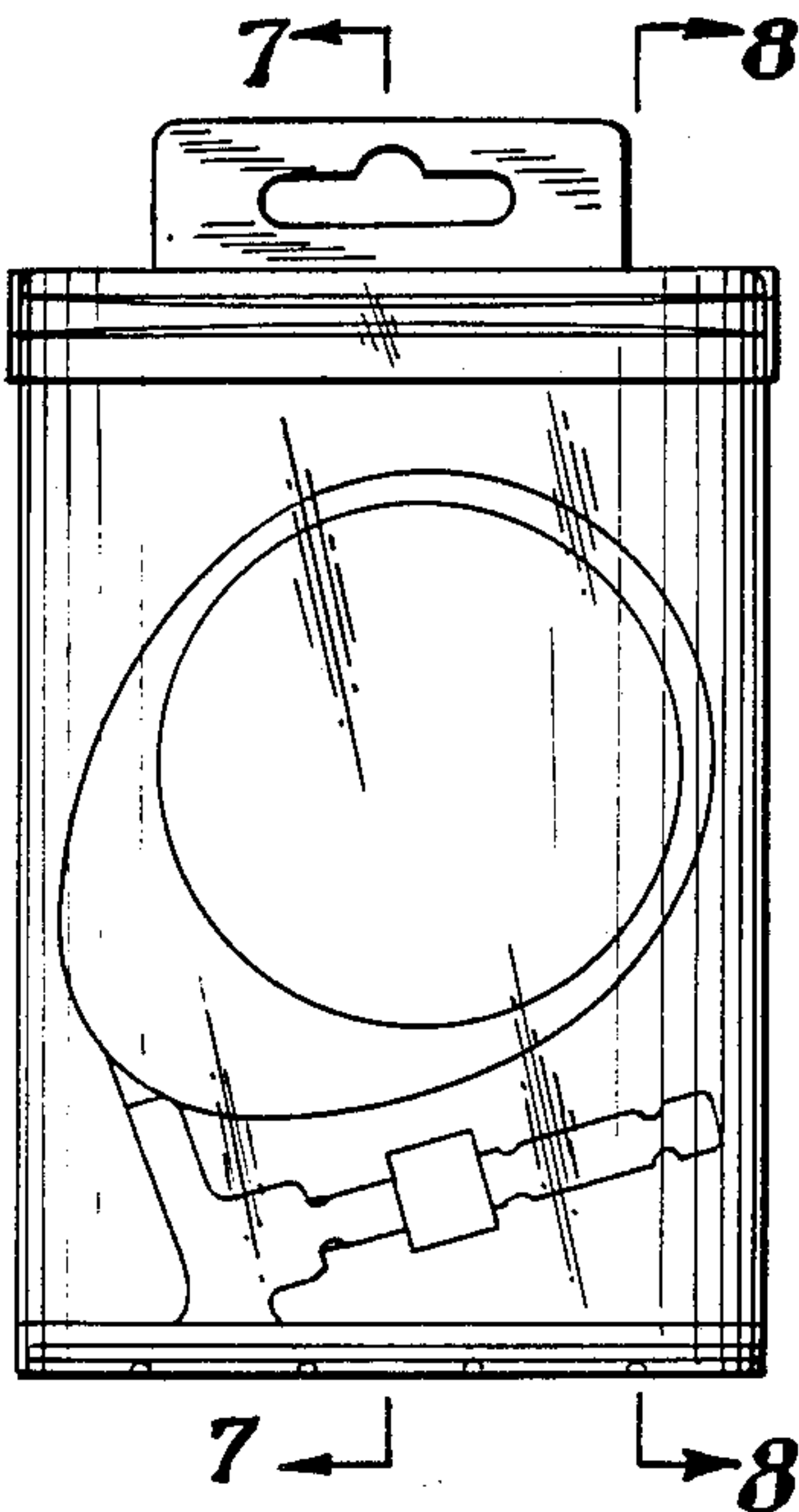
[54] PACKAGE FOR EARPHONE
[75] Inventor: Yoshie Nagasaka, Tokyo, Japan
[73] Assignee: Sony Corporation, Tokyo, Japan
[**] Term: 14 Years
[21] Appl. No.: 245,382
[22] Filed: Sep. 16, 1988
[30] Foreign Application Priority Data
Mar. 17, 1988 [JP] Japan 63-10883
[52] U.S. Cl. D9/415
[58] Field of Search D9/415, 418, 337, 455;
206/461-471, 438, 44 R, 45.31, 45.33, 570, 581,
38

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[57] CLAIM
The ornamental design for a package for earphone, as shown.

DESCRIPTION
FIG. 1 is a front elevation of a package for earphone showing my new design;
FIG. 2 is a rear elevation view thereof;
FIG. 3 is a left-side elevation thereof;
FIG. 4 is a right-side elevation thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a sectional elevation taken along line 7—7 of FIG. 1; and
FIG. 8 is a sectional elevation taken along line 8—8 of FIG. 1.



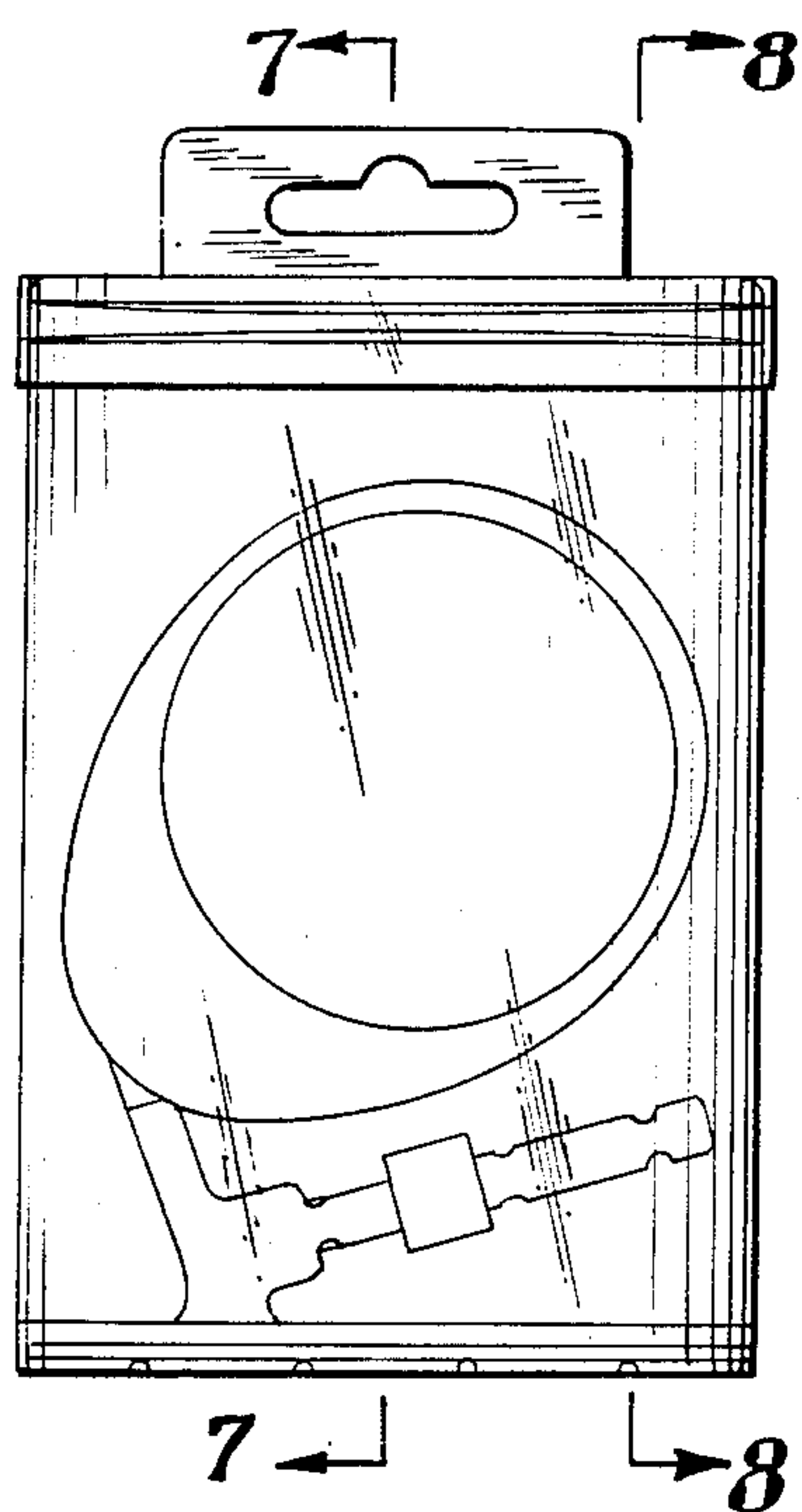


FIG. 1

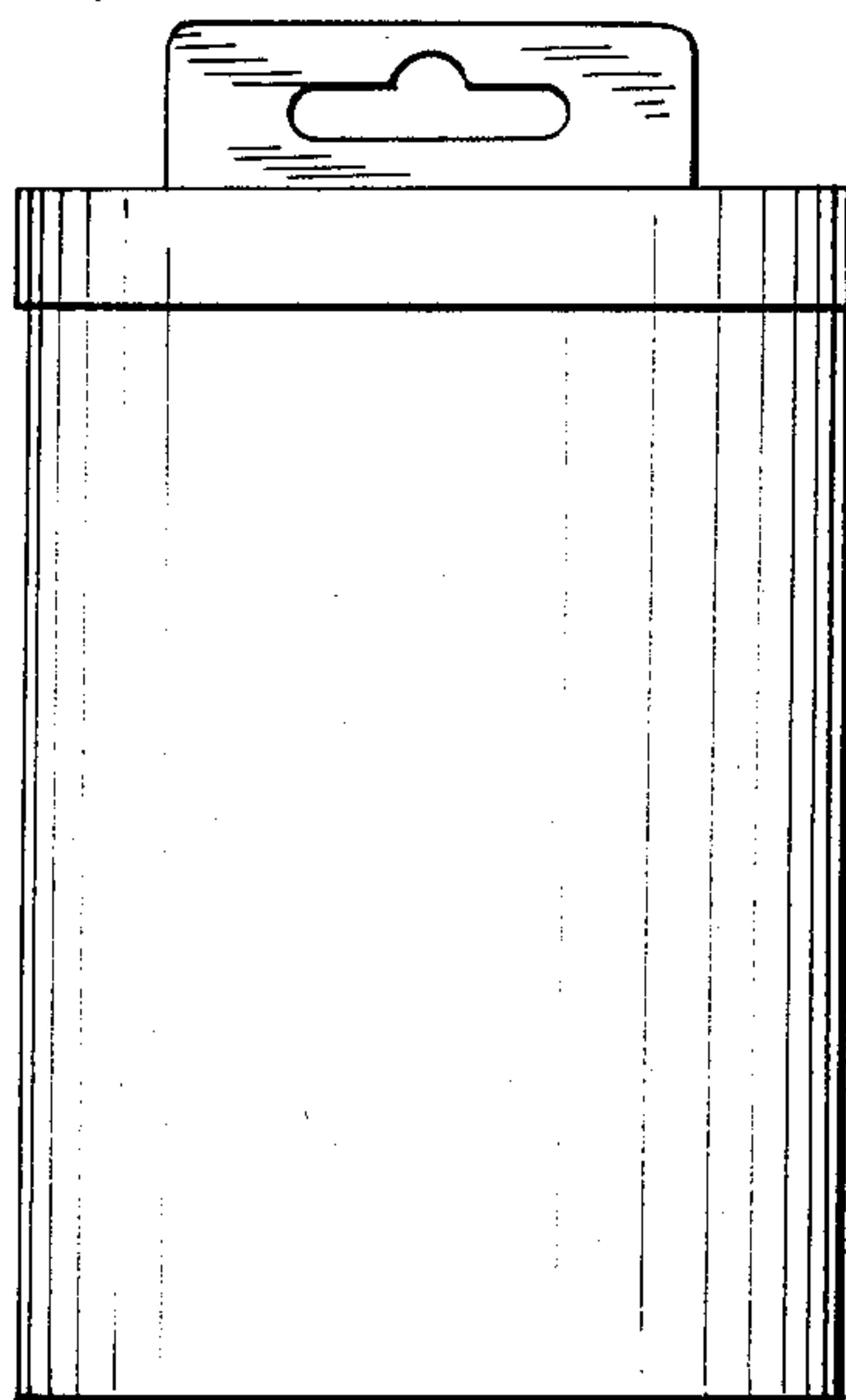


FIG. 2

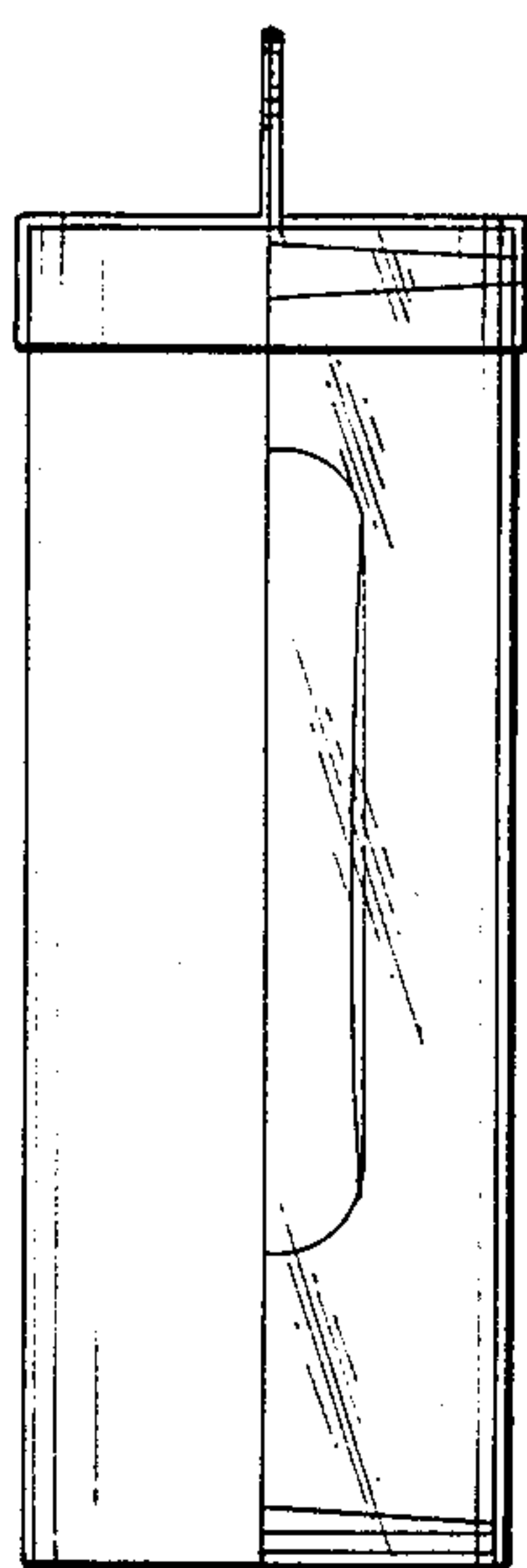


FIG. 3

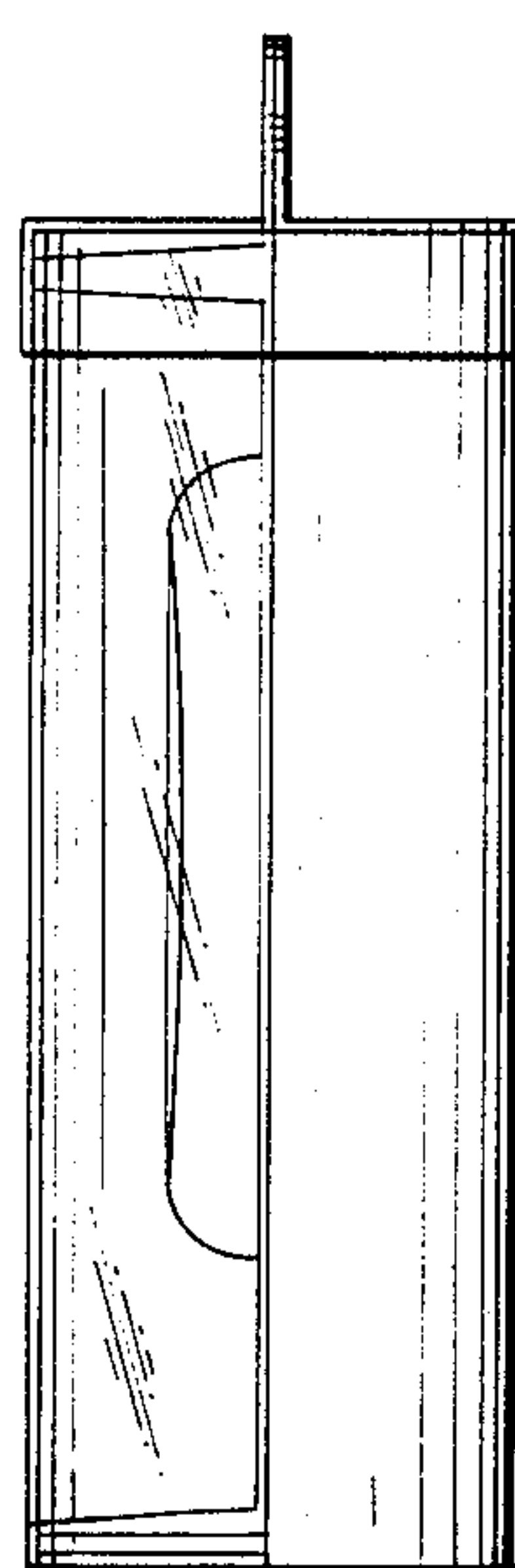


FIG. 4

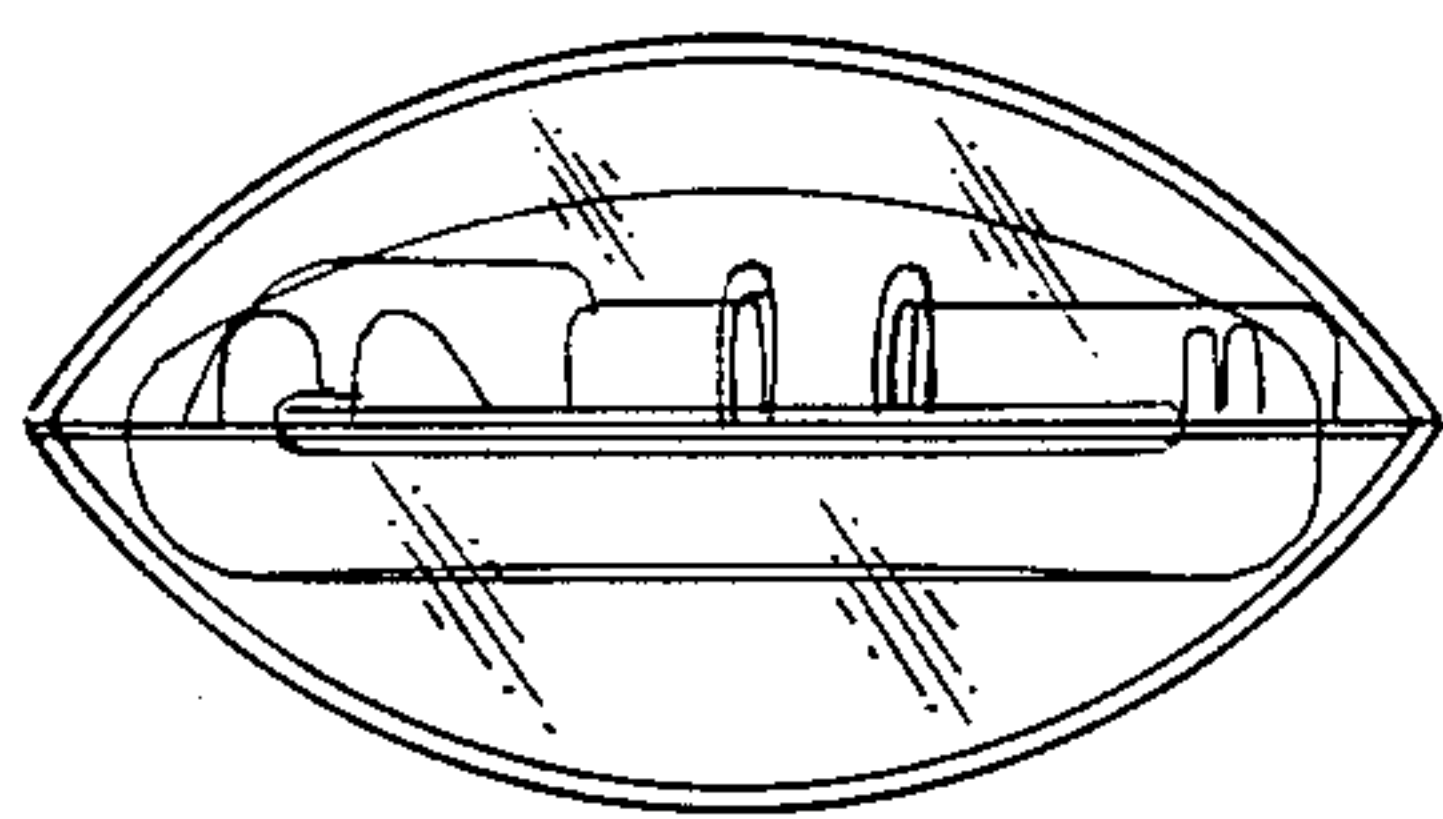


FIG. 5

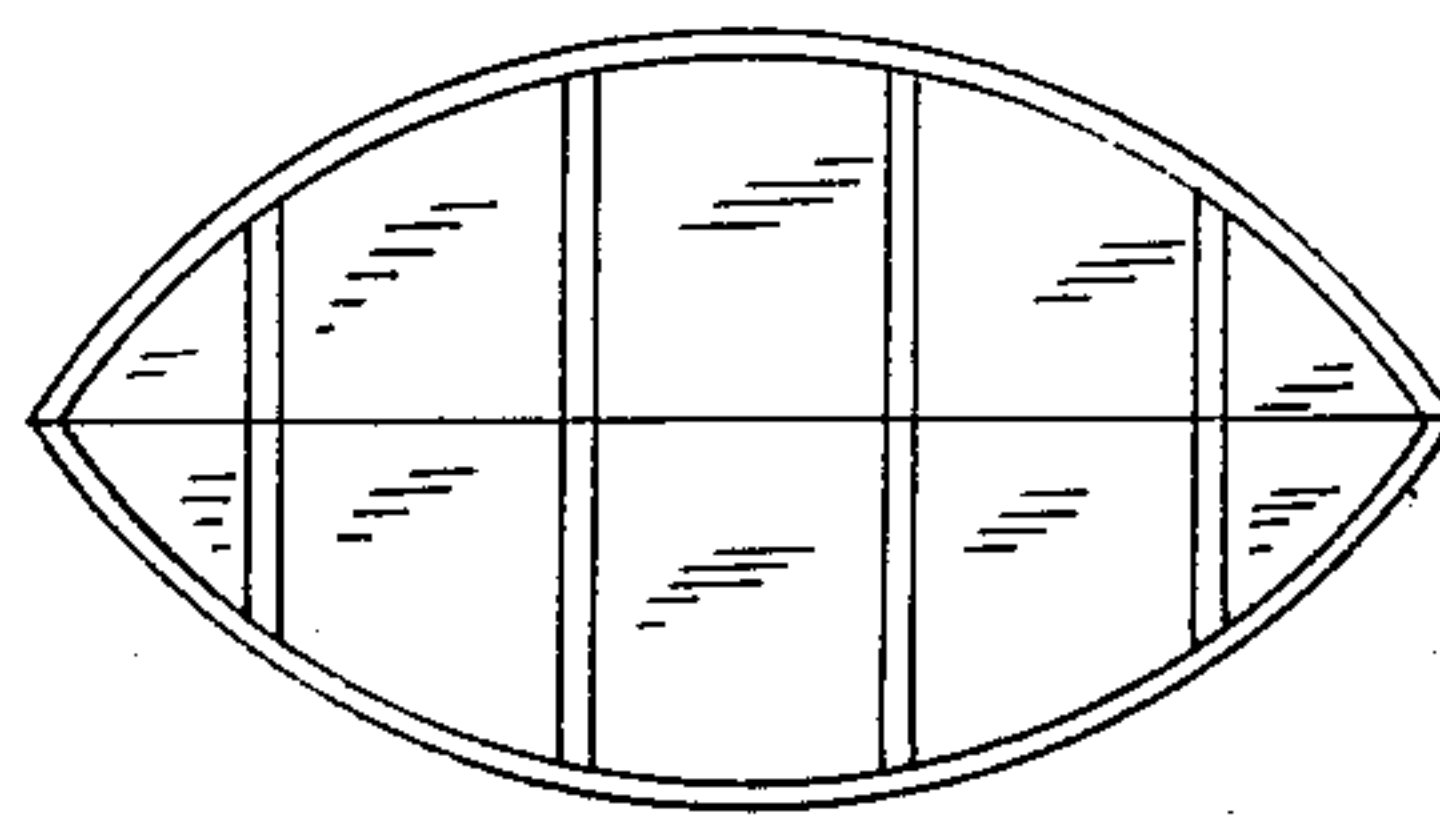


FIG. 6

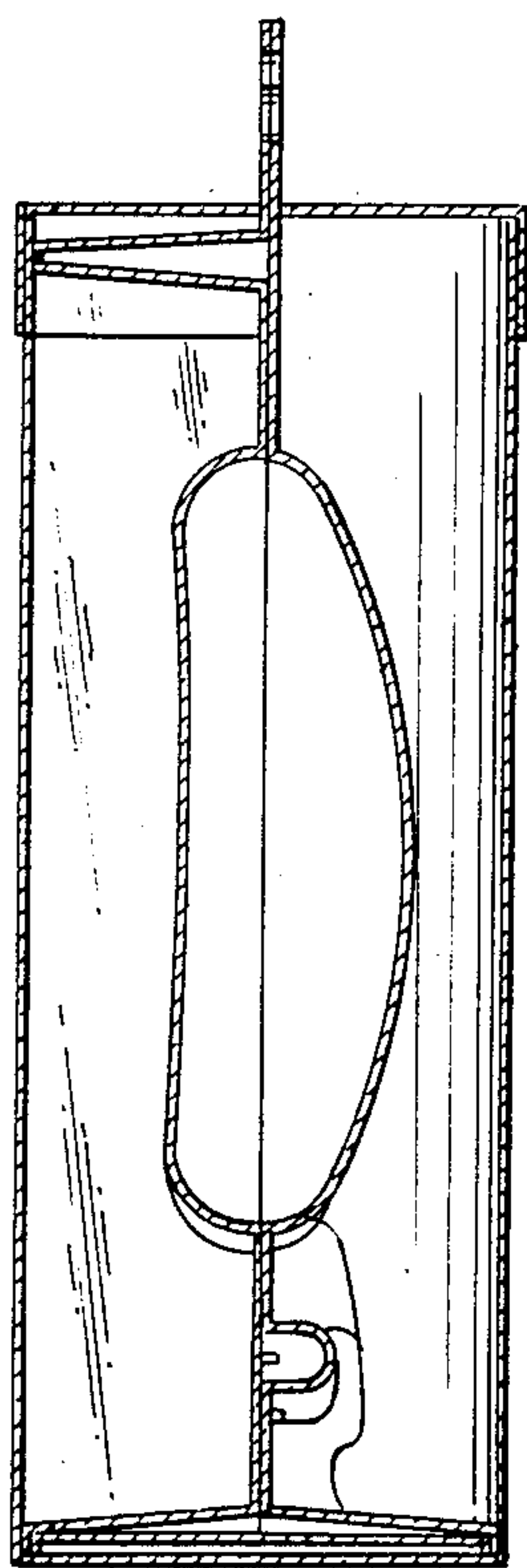


FIG. 7

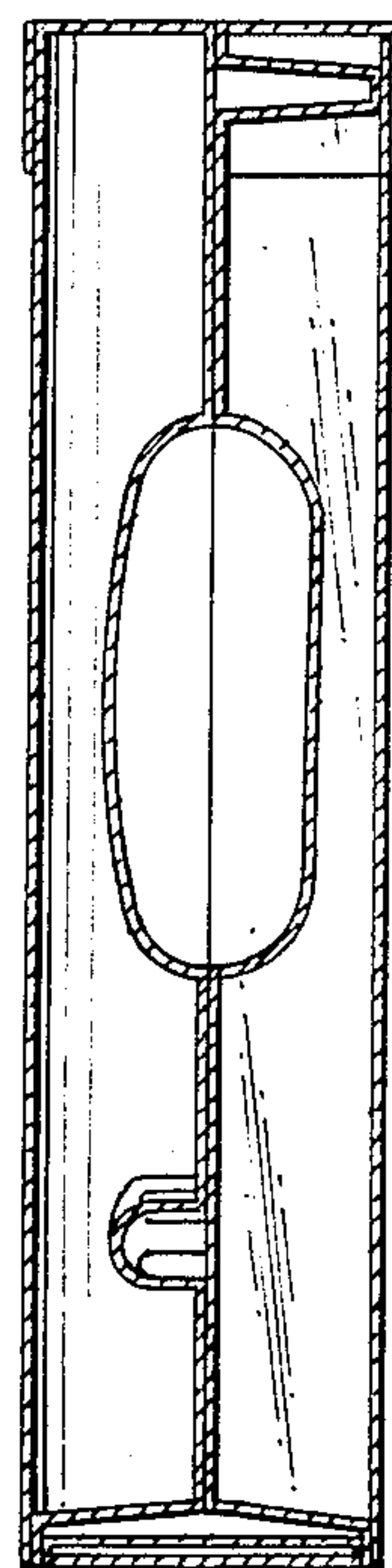


FIG. 8